

CLAIMS

1. A molding method for manufacturing a resin molding by charging a resin composition including fibrous filler (A) and resin (B) in molten state into a die by injection, wherein the resin composition contains not less than 7 wt% to less than 30 wt% of the fibrous filler (A) and more than 70 wt% to not exceeding 93 wt% of the resin (B),
5 and that comprises the steps of;

(a) charging the resin composition in molten state into the die for shaping purpose when a temperature of the die is in the range of [the Vicat softening point minus 20°C] of the resin (B) to less than a melting point thereof, when the resin (B) is crystalline resin,
10 or charging the resin composition in molten state into the die for shaping purpose when a temperature of the die is in the range of [the Vicat softening point minus 20°C] to [the Vicat softening point plus 20°C] of the resin (B), when the resin (B) is non-crystalline resin; and

(b) cooling down the die to a temperature which allows taking-out of a molded
15 product, after the shaping is performed.

2. A molding method for manufacturing a resin molding by extruding a resin composition including fibrous filler (A) and resin (B) to be converted into a molten parison, holding the parison within a die, and by blowing gas into the parison inside,
20 wherein the resin composition contains more than 7 wt% to less than 30 wt% of the fibrous filler (A) and more than 70 wt% to less than 93 wt% of the resin (B),
and that comprises the steps of;

(a) blowing gas into the parison inside for shaping purpose when a temperature of the die is in the range of [the Vicat softening point minus 20°C] of the resin (B) to less
25 than a melting point thereof, when the resin (B) is crystalline resin,

or blowing a gas into the parison inside for shaping purpose when a temperature of the die is in the range of [the Vicat softening point minus 20°C] to [the Vicat softening point plus 20°C] of the resin (B), when the resin (B) is non-crystalline resin; and

(b) cooling down the die to temperature which allows taking-out of a molded

product after the shaping is performed

3. The molding method according to Claim 1 or Claim 2, wherein if the resin (B) is crystalline resin, after shaping of the resin composition is performed, a temperature of the die is held for preset period in the range of [crystallization temperature minus 15°C] to [crystallization temperature plus 10°C] of the resin (B).
4. The molding method according to either of Claims 1 through 3, wherein shaping of the resin composition is performed when a temperature of the die is in the range of [the Vicat softening temperature minus 10°C] of the resin (B) to [melting point minus 10°C], when the resin (B) is crystalline resin,
or performed when a temperature of the die is in the range of [the Vicat softening temperature minus 10°C] to [the Vicat softening temperature plus 10°C] of the resin (B), when the resin (B) is non-crystalline resin.
5. The molding method according to either of Claims 1 through 4, wherein after shaping of the resin composition is performed, a temperature of the die is held for preset period in the range of [crystallization temperature minus 10°C] to [crystallization temperature] of the resin (B), when the resin (B) is crystalline resin.
6. The molding method according to either of Claims 1 through 5, wherein the resin composition contains not less than 10 wt% to not exceeding to 25 wt% of the fibrous filler (A).
7. A resin molding manufactured by the molding method according to either of Claims 1 through 6,
8. A resin molding containing not less than 7 wt% to less than 30 wt% of a fibrous fiber (A) and more than 70 wt% to not exceeding 93 wt% of a resin (B), wherein surface

roughness is less than 5 μm and an image representation of 1 mm square rectangular frame reflected on the surface can be discriminated.

9. A resin molding having an emboss on the surface and containing not less than 7
5 wt% to less than 30 wt% of a fibrous fiber (A) and more than 70 wt% to not exceeding 93
wt% of a resin (B), and is characterized by either one of the following 1 or 2.

(1) Die transcription rate is more than 90% for such a case where emboss is
provided over whole surface of a resin molding;

- (2) Die transcription rate is more than 90% and surface roughness of such an area
10 where there is no emboss is less than 5 μm for such a case where emboss is provided in
part of a resin molding.

10. The resin molding according to Claim 8 or Claim 9, wherein the resin
composition contains not less than 10 wt% to not exceeding to 25 wt% of the fibrous filler
15 (A).